

ABSTRACT OF THE DISCLOSURE

[55] A semiconductor device is provided with outer leads which show themselves in the bottom surface of the resin encapsulated body. This structure eliminates minute chipping and cracking near the resin which has been cut in the vicinity of the end of the outer lead. The semiconductor device is produced in such a way that a push-back-portion is previously arranged between leads of the lead frame and the push-back-portion is pushed down after molding. The resulting semiconductor device has outer leads such that there is no encapsulating resin between outer leads which show themselves in the bottom surface of the resin encapsulated body.